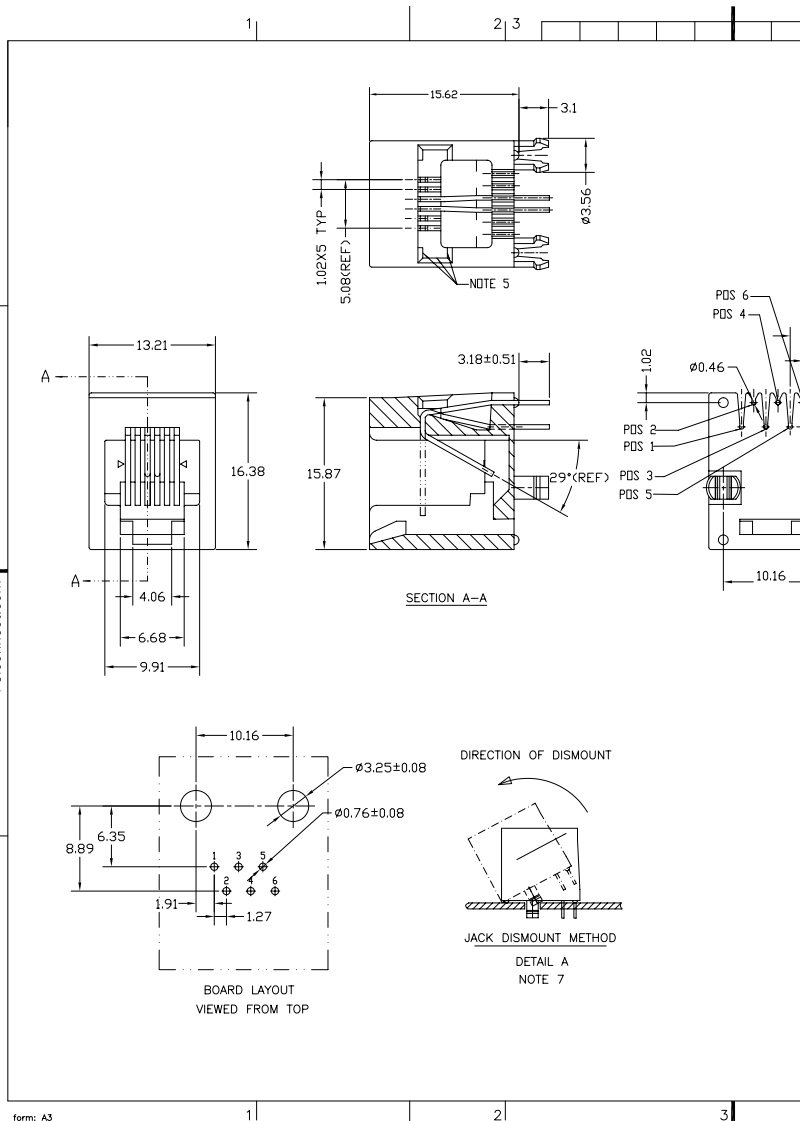


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1.LF PRODUCTS MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

2.THE HOUSING WILL WITHSTAND EXPOSURE TO 260° PEAK TEMPERATURE FOR 3.5 SEC IN A WAVE SOLDER APPLICATION WITH A 1.57mm MIN THICK CIRCUIT BOARD. SLIGHT DEFORMATION OF SNAP PEGS MAY OCCUR AT 260-265°C WHICH WILL NOT AFFECT THE FUNCTION OF THE PRODUCT.

3.LEAD FREE OR ROHS DIRECTIVE LABELLING TO BE PROVIDED AS PER GS-14-920 FOR LEADFREE VERSION.

10037501 - X X 2 LF
 LEAD FREE
 POS LOADED
 0 - 3&4
 1 - 2,3,4&5
 2 - ALL POS
 CONTACT PLATING
 0 - 30u" GXT
 1 - 30u" GOLD

- NOTES :
- INSULATOR MATERIAL -THERMOPLASTIC UL 94 V0 BLACK HOUSING : NYLON 66 25% GLASS FILLED UL94 V0 THE HOUSING WILL WITHSTAND EXPOSURE TO 260-265°C FOR 3.5 SECONDS IN NORMAL WAVE SOLDERING APPLICATION. USE PROTECTIVE ADHESIVE(KAPTON OR TEFLON) OR PROTECTIVE METALLIC DEVICE ON THE AREAS WHICH ARE DIRECTLY EXPOSED TO WAVE SOLDERING AS IT IS USED IN CLASSICAL LEADED WAVE SOLDERING.
 - CONTACT : $\varnothing 0.46$ mm PHOSPHORBRONZE WIRE
 - WIRE MUST BE CONTAINED WITHIN COMB SHELVES.
 - PACKAGING IN TUBE
 - SCRATCH MARKS ACCEPTABLE ON THESE SURFACES.
 - JACK IS FOR 1,57mm THICK PCB.
 - SHOULD THE JACK NEED TO BE DISMOUNTED FROM THE PCB, PLS REMOVE JACK AS PER RECOMMENDED METHOD HEREIN. (DETAIL A) NIPPING THE LEGS OF THE PEG TOGETHER IS DISALLOWED, OTHERWISE LEG BREAKAGE MAY OCCUR.

mat'l. code SEE NOTES 1 & 2		surface ISO 1302	tolerance ISO 406 ISO 1101	projection MM	product family MODJACK
ltr	ecn no dr date	tolerances unless otherwise specified		MM	title 6 POS VER MOD JACK WITH SNAP PEGS
B	108-0157 NPM 2009-04-06	angles	linear	scale 2:1	dwg no 10037501
C	109-0083 NPM 2009-05-21	dr	enfr	chr	sheet 1 of 1 size A4
		0°±2°	HRAN V.N 2006-11-01	NEBU P.M 2009-05-21	type Product Customer Drawing
			appd	NEBU P.M 2009-05-21	
sheet index	revision sheet	C			
1	1				